- Meets or Exceeds the Requirements of IOS 8802.3:1989 and ANSI/IEEE Std 802.3-1988
- Interdevice Loop-Back Paths for System Testing
- Squelch Function Implemented on the **Receiver Inputs**
- Drivers Will Drive a Balanced 78- $\Omega$  Load
- **Transformer Coupling Not Required in** System
- Power-Up/Power-Down Protection (Glitch Free)
- **Isolated Ground Pins for Reduced Noise** Coupling
- **Fault-Condition Protection Built into the Device**
- **Driver Inputs Are Level-Shifted ECL** Compatible

'	. • .	***	
TXI1[	1	U <sub>24</sub>	TXO1
TXEN1[	2	23	TXO1
LOOP1[	3	22	] <u>∨cc</u>
GND[	4	21	RXI1
RXEN1[	5	20	] RXI1
RXO1[	6	19	GND
RXO2[	7	18	GND
RXEN2[	8	17	RXI2
GND[	9	16	RXI2
LOOP2	10	15	] v <sub>cc</sub>
TXEN2[	11	14	TXO2
TXI2[	12	13	] TXO2

DW OR NT PACKAGE

(TOP VIEW)

### description

The SN75ALS085 is a monolithic, high-speed, advanced low-power Schottky, dual-channel driver/receiver device designed for use in the AUI of ANSI/IEEE Std 802.3-1988. The two drivers on the device drive a 78- $\Omega$ balanced, terminated twisted-pair transmission line up to a maximum length of 50 meters. In the off (idle) state, the drivers maintain minimal differential output voltage on the twisted-pair line and, at the same time, remain within the required output common-mode range.

With the driver enable (TXEN) high, upon receiving the first falling edge into the driver input, the differential outputs will rise to full-amplitude output levels within 25 ns. The output amplitude is maintained for the remainder of the packet. After the last positive packet edge is transmitted into the driver, the driver will maintain a minimum of 70% full differential output for a minimum of 200 ns, then decay to a minimum level for the reset (idle) condition within 8 μs. Disabling the driver by taking the driver enable low will also force the output into the idle condition after the normal 8-us timeout. While operating, the drivers are able to withstand a set of fault conditions and not suffer damage due to the faults being applied. The drivers power up in the idle state to ensure that no activity is placed on the twisted-pair cable that could be interpreted as network traffic.

The line receiver squelch function interfaces to a differential twisted-pair line terminated external to the device. The receiver squelch circuit allows differential receive signals to pass through as long as the input amplitude and pulse duration are greater than the minimum squelch threshold. This ensures a good signal-to-noise ratio while the data path is active and prevents system noise from causing false data transitions during line shutdown and line-idle conditions. The RXO outputs default to a high level and the RXEN outputs default to a low level while the squelch function is blocking the data path through the receiver (idle). The line receiver squelch will become active within 50 ns when the input squelch threshold is exceeded. RXEN will be driven high when the squelch circuit is allowing data to pass through the receiver. The receiver squelch circuit can also withstand a set of fault conditions while operating without causing permanent damage to the device.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



### description (continued)

The purpose of the loop functions is to provide a means by which system data path verification can be done to isolate faulty interfaces and assist in network diagnosis. The LOOP pins are TTL compatible and must be held high for normal operation. When LOOP1 is taken low, the output of driver 1 (TXO1) immediately goes into the idle state. Also, the input to receiver 1 is ignored and a path from TXI1 to RXO1 is established. When LOOP1 is taken back high, driver 1 and receiver 1 revert back to their normal operation. When LOOP2 is taken low, a similar data path is established between TXI1 and RXO2. TXEN1 must be high for the loop functions to operate and TXEN1 can be used to gate the loop function if desired. During loop operation, the respective receiver enable output (RXEN) will reflect the status of TXEN1.

### **Function Tables**

#### $RECEIVER - \overline{LOOP} = H$

	OUTPU					
RXI		PREVIOUS RXEN	RXEN	RXO		
$V_{ID} = 1315 \text{ mV to } -175 \text{ mV},$	t <sub>W</sub> < 25 ns	L	L	Н		
$V_{ID} = -275 \text{ mV to } -1315 \text{ mV},$	$t_W > 50 \text{ ns}$	X	Н	L		
$V_{ID} = 318 \text{ mV to } 1315 \text{ mV},$	t <sub>W</sub> < 142 ns	Н	Н	Н		
$V_{ID} = 318 \text{ mV to } 1315 \text{ mV},$	t <sub>W</sub> > 187 ns	X	L	Н		

H = high level, L = low level, X = don't care

#### $DRIVER - \overline{LOOP} = H$

	DKIVEK - EGGI - II									
TXI	TXEN	PREVIOUS TXO	OUTPUT TXO							
L	L	Idle	Idle							
Н	L	Idle	Idle							
↓	Н	Idle	L							
L	Н	Active	L							
H < 260 μs	Н	Active	Н							
H > 8 μs	Н	Active	Idle							
L	L > 8 μs	Active	Idle							
H < 260 ns	L > 8 μs	Active	Idle							
H < 260 ns	L < 260 ns	Active	Н							
H > 8 μs	L < 260 ns	Active	Idle							
L	L < 260 ns	Active	L							

 $H = V_I \geq V_T \; max, \; L = V_I \leq V_T \; min$ 



## SN75ALS085 LAN ACCESS UNIT INTERFACE DUAL DRIVER/RECEIVER

SLLS054B - APRIL 1989 - REVISED MAY 1995

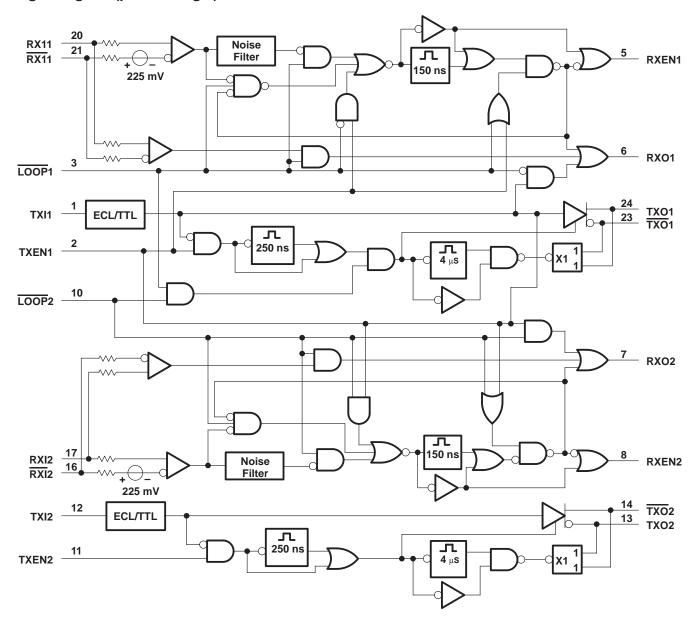
## **Function Tables (continued)**

LOOP

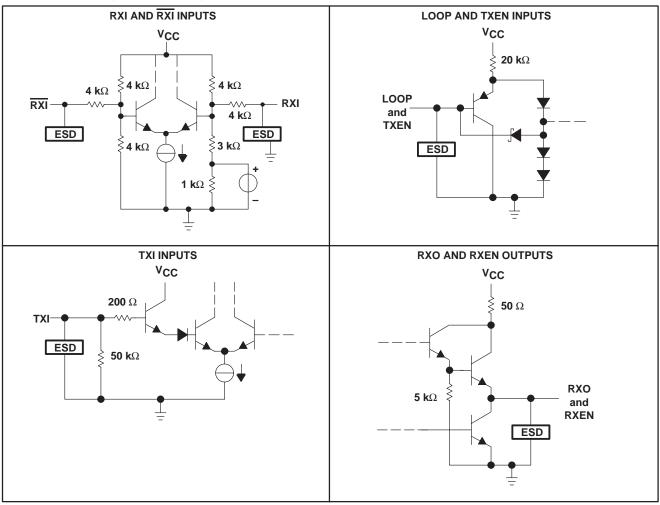
	INPUTS							OUTPUTS		
LOOP1	LOOP2	TXI1	TXEN1	RXI1	RXI2	RXO1	RXO2	RXEN1	RXEN2	TXO1
L	L	L	Н	Χ	Χ	L	L	Н	Н	Idle
L	L	Н	Н	Χ	Χ	Н	Н	Н	Н	Idle
L	L	Χ	L	Χ	Χ	Н	Н	L	L	Idle
L	Н	L	Н	Х	Normal	L	Normal	Н	Normal	Idle
L	Н	Н	Н	Χ	Normal	Н	Normal	Н	Normal	Idle
L	Н	Χ	L	Χ	Normal	Н	Normal	L	Normal	Idle
Н	L	L	Н	Normal	Χ	Normal	L	Normal	Н	Idle
Н	L	Н	Н	Normal	Χ	Normal	Н	Normal	Н	Idle
Н	L	Χ	L	Normal	Χ	Normal	Н	Normal	L	Idle
Н	Н	Normal	Normal	Normal						

H = high level, L = low level, X = don't care

### logic diagram (positive logic)



## schematics of inputs and outputs



## SN75ALS085 LAN ACCESS UNIT INTERFACE DUAL DRIVER/RECEIVER

SLLS054B - APRIL 1989 - REVISED MAY 1995

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V <sub>CC</sub> (see Note 1)	6 V
TXI and LOOP input voltage, V <sub>I</sub>	5.5 V
TXO and TXO output voltage, VO	16 V
RXI and $\overline{\text{RXI}}$ input voltage, V <sub>I</sub>	
RXO and RXEN output voltage, V <sub>O</sub>	5.5 V
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T <sub>A</sub>	0°C to 70°C
Storage temperature range, T <sub>stg</sub>	– 65 °C to 150 °C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

NOTE 1: Voltage values are with respect to network ground terminal.

#### **DISSIPATION RATING TABLE**

PACKAGE	$T_{\mbox{\scriptsize A}} \leq 25^{\circ}\mbox{\scriptsize C}$ POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING
DW	1350 mW	10.8 mW/°C	864 mW
NT	1250 mW	10.0 mW/°C	800 mW

## recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	4.75	5	5.25	V
Common-mode voltage at RXI inputs, V <sub>IC</sub>	1		4.2	V
Differential voltage between RXI inputs, V <sub>ID</sub>	±318		±1315	mV
High-level input voltage, LOOP and TXEN, VIH	2			V
Low-level input voltage, LOOP and TXEN, V <sub>IL</sub>			0.8	V
High-level output current, RXO and RXEN, I <sub>OH</sub>			- 0.4	mA
Low-level output voltage, RXO and RXEN, IOL			16	mA
Setup time, driver mode, TXEN high before TXI↓, t <sub>SU1</sub> (see Figure 7)	10			ns
Setup time, loop mode, LOOP low before TXEN↑, t <sub>Su2</sub> (see Figure 9)	15			ns
Setup time, loop mode, TXEN high before TXI↓, t <sub>Su3</sub> (see Figure 9)	10			ns
Hold time, loop mode, TXEN high after TXI↑, th1 (see Figure 8)	10			ns
Hold time, loop mode, LOOP low after TXEN↓, th2 (see Figure 8)	15			ns
Operating free-air temperature, T <sub>A</sub>	0		70	°C



# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER		TEST C	ONDITIONS	MIN	MAX	UNIT
٧ıK	Clamp voltage at all inputs		$I_{I} = -18 \text{ mA}$			-1.5	V
				V <sub>CC</sub> = 4.75 V	3.202	3.752	
			T <sub>A</sub> = 0°C	V <sub>CC</sub> = 5 V	3.389	3.998	V
				V <sub>CC</sub> = 5.25 V	3.577	4.244	
				V <sub>CC</sub> = 4.75 V	3.213	3.797	
V <sub>(TO)</sub>	Driver input (TXI) threshold voltage		T <sub>A</sub> = 25°C	V <sub>CC</sub> = 5 V	3.400	4.043	V
` ′				V <sub>CC</sub> = 5.25 V	3.588	4.289	
				V <sub>CC</sub> = 4.75 V	3.239	3.849	
			T <sub>A</sub> = 70°C	V <sub>CC</sub> = 5 V	3.426	4.095	V
				V <sub>CC</sub> = 5.25 V	3.614	4.341	
	Receiver differential input threshold voltage					-275	mV
		Idle	TXEN at 0.8 V, LOOP2 at 2 V,	LOOP1 at 2 V, See Figure 1	1	4.2	
Voc	Driver output (TXO) common-mode voltage	Active	TXEN at 2 V, LOOP2 at 2 V, See Figure 1	LOOP1 at 2 V, TXI at 3.2 V,	1	4.2	V
		Active	TXEN at 2 V, LOOP2 at 2 V, See Figure 1	LOOP1 at 2 V, TXI at 4.4 V,	1	4.2	
		Idle	TXEN at 0.8 V, LOOP2 at 2 V,	LOOP1 at 2 V, See Figure 1		±40	
V <sub>OD</sub>	Driver output (TXO) differential voltage	Active	TXEN at 2 V, LOOP2 at 2 V, See Figure 1	LOOP1 at 2 V, TXI at 3.2 V,	- 600	1315	mV
		Active	TXEN at 2 V, LOOP2 at 2 V, See Figure 1	LOOP1 at 2 V, TXI at 4.4 V,	600	1315	
Vон	High-level output voltage	RXO, RXEN	$I_{OH} = -0.4 \text{ mA}$		2.4		V
VOL	Low-level output voltage	RXO, RXEN	I <sub>OL</sub> = 16 mA			0.5	V
		TXEN, LOOP	V <sub>I</sub> = 2 V			20	
۱н	High-level input current	TXI	V <sub>I</sub> = 4.5 V			400	μΑ
		RXI, RXI	$V_{ID} = -0.5 V$ ,	V <sub>IC</sub> = 1 V to 4.2 V		1000	
		TXEN, LOOP	V <sub>I</sub> = 0.8 V			-200	
ļ	Low lovel input current	TXI	V <sub>I</sub> = 3.1 V			100	mA
lIL.	IL Low-level input current		V <sub>I</sub> = 0.3 V		4	10	IIIA
		RXI, RXI	$V_{ID} = 0.5 V,$	$V_{IC}$ = 1 V to 4.2 V		1000	
lod	Driver differential output current	Idle	TXEN at 0.8 V, LOOP2 at 2 V,	LOOP1 at 2 V, See Figure 2		±4	mA
los	Short-circuit output current <sup>†</sup>	RXO, RXEN	V <sub>O</sub> at 0 V, RXI at 2 V	RXI at 3 V,	- 40	- 150	mA
Icc	Supply current		LOOP2 at 2 V, TXI at 4.5 V,	TXEN at 2 V, Outputs open		225	mA

<sup>†</sup> Not more than one output should be shorted at a time, and the duration of the test should not exceed 1 second.



## SN75ALS085 LAN ACCESS UNIT INTERFACE DUAL DRIVER/RECEIVER

SLLS054B - APRIL 1989 - REVISED MAY 1995

# electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (continued)

PARAMETER		TEST CO	NDITIONS <sup>†</sup>	MIN	MAX	UNIT
	TXO shorted to TXO,	Current measu	red in short		150	
	TXO at 0 V,	TXO is open,	Current measured at TXO		150	
	TXO is open,	TXO at 0,	Current measured at TXO		150	
Driver fault condition current	TXO at 0 V,	TXO at 0 V,	Current measured at TXO and TXO		150	mA
	TXO at 16 V,	TXO is open,	Current measured at TXO		150	
	TXO is open,	TXO at 16 V,	Current measured at TXO		150	
	TXO at 16 V,	TXO at 16 V,	Current measured at TXO and TXO		150	
	RXI shorted to RXI,	Current measu	red in short		10	
	RXI at 0 V,	RXI is open,	Current measured at RXI		3	
	RXI is open,	RXI at 0 V,	Current measured at RXI		3	
Receiver fault condition current	RXI at 0 V,	RXI at 0 V,	Current measured at RXI and RXI		3	mA
	RXI at 16 V,	RXI at open,	Current measured at RXI		10	
	RXI at open,	RXI at 16 V,	Current measured at RXI		10	
	RXI at 16 V,	RXI at 16 V,	Current measured at RXI and RXI		10	

<sup>†</sup> Fault conditions should be measured on only one channel at a time.



# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

### driver

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST C	CONDITIONS	MIN	MAX	UNIT
<sup>t</sup> PLH	Propagation delay time, low-to-high level output	TXI	TXO, TXO	TXEN at 2 V,	See Figure 3		15	ns
tPHL	Propagation delay time, high-to-low level output	TXI	TXO, TXO	TXEN at 2 V,	See Figure 3		15	ns
t <sub>PIL</sub>	Propagation delay time, idle-to-low level output	TXI	TXO, TXO	TXEN at 2 V,	See Figure 4		25	ns
t <sub>PIL</sub>	Propagation delay time, idle-to-low level output	TXEN	TXO, TXO	TXI at 3.2 V,	See Figure 5		25	ns
t <sub>W</sub>	Output pulse duration from low-to-high level to 70% output level		TXO, TXO	TXEN at 2 V,	See Figure 6	260	8000	ns
VOD(U)	Driver output differential undershoot voltage	TXI	TXO, TXO	TXEN at 2 V,	See Figure 6		-100	mV
t <sub>sk</sub>	Driver caused signal skew tPLH - tPHL	TXI	TXO, TXO	TXEN at 2 V,	See Figure 3		±3	ns
t <sub>r</sub>	Rise time, TXO, TXO			TXEN at 2 V,	See Figure 3	1	5	ns
t <sub>f</sub>	Fall time, TXO, TXO			TXEN at 2 V,	See Figure 3	1	5	ns

### receiver

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT
<sup>t</sup> PLH	Propagation delay time, low-to-high level output	RXI, RXI	RXO	V <sub>IC</sub> = 1 V to 4.2 V, See Figure 10		15	ns
<sup>t</sup> PHL	Propagation delay time, high-to-low level output	RXI, RXI	RXO	V <sub>IC</sub> = 1 V to 4.2 V, See Figure 10		15	ns
<sup>t</sup> PLH	Start-up delay time, low-to-high level output	RXI, RXI	RXEN	$V_{IC} = 1 \text{ V to } 4.2 \text{ V},  V_{ID} = -500 \text{ mV},$ See Figure 12		55	ns
tPHL	Shutdown delay time, high-to-low level output	RXI, RXI	RXEN	$V_{IC} = 1 \text{ V to } 4.2 \text{ V},  V_{ID} = 500 \text{ mV},$ See Figure 12	142	181	ns
t <sub>sk</sub>	Receiver caused signal skew (tpLH - tpHL)	RXI, RXI	RXO	$V_{IC}$ = 1 V to 4.2 V, $V_{ID}$ = 500 mV, See Figure 10		±3	ns
t <sub>W</sub>	Pulse duration at RXI and RXI (to not activate squelch)			$V_{IC} = 1 \text{ V to } 4.2 \text{ V},  V_{ID} = -175 \text{ mV},$ See Figure 11	25		ns
t <sub>W</sub>	Pulse duration at RXI and RXI (to activate squelch)			$V_{IC} = 1 \text{ V to } 4.2 \text{ V},  V_{ID} = -275 \text{ mV},$ See Figure 11		50	ns
t <sub>r1</sub>	Rise time, RXO			$V_{IC}$ = 1 V to 4.2 V, $V_{ID}$ = ±500 mV, See Figure 10	1	8	ns
t <sub>r2</sub>	Rise time, RXEN			$V_{IC}$ = 1 V to 4.2 V, $V_{ID}$ = ±500 mV, See Figure 12	1	8	ns
t <sub>f1</sub>	Fall time, RXO			$V_{IC}$ = 1 V to 4.2 V, $V_{ID}$ = ±500 mV, See Figure 10	1	8	ns
t <sub>f2</sub>	Fall time, RXEN			$V_{IC}$ = 2.5 V, $V_{ID}$ = ±500 V, See Figure 12	1	8	ns
t <sub>V</sub>	RXO valid after RXEN high			See Figure 10	-10	15	ns

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature

### loop

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN MAX	UNIT
<sup>t</sup> PLH	Propagation delay time, low-to-high level output	TXI	RXO	LOOP at 0.8 V, TXEN at 2 V, See Figure 13	30	ns
<sup>t</sup> PHL	Propagation delay time, high-to-low level output	TXI	RXO	LOOP at 0.8 V, TXEN at 2 V, See Figure 13	30	ns
<sup>t</sup> PLH	Propagation delay time, low-to-high level output	TXEN	RXEN	LOOP at 0.8 V, See Figure 14	50	ns
tPHL	Propagation delay time, high-to-low level output	TXEN	RXEN	LOOP at 0.8 V, See Figure 14	50	ns

### PARAMETER MEASUREMENT INFORMATION

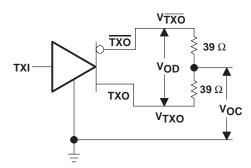


Figure 1. Driver Test Circuit

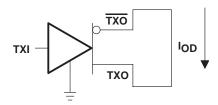
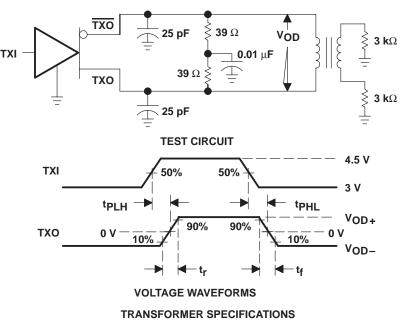


Figure 2. Driver Test Circuit



Turns Ratio	1:1
Magnetizing Inductance	26 to 30 μH
Winding Resistance	$0.6~\Omega$ Max
Rise Time 10% to 90%	5 ns Max
Interwinding Capacitance	25 pF
Leakage Inductance	0.25 μH Max
Inductive Q	1250 Min

Figure 3. Test Circuit and Voltage Waveforms

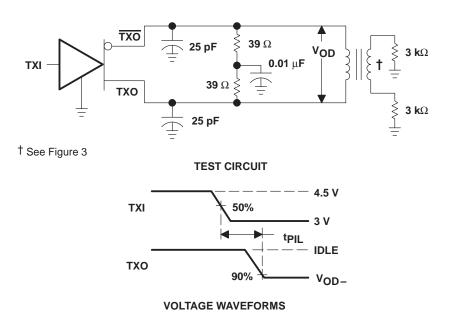


Figure 4. Test Circuit and Voltage Waveforms

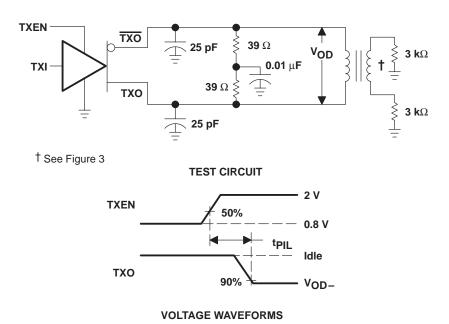


Figure 5. Test Circuit and Voltage Waveforms

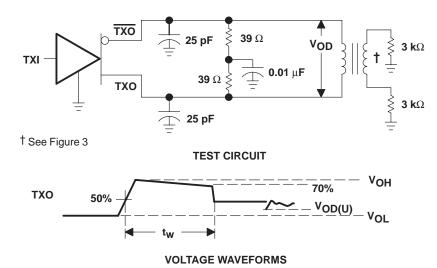
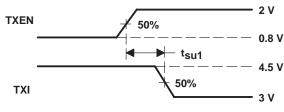


Figure 6. Test Circuit and Voltage Waveforms



NOTE: Input  $t_{\Gamma} \le 5$  ns;  $t_{f} \le 5$  ns

Figure 7

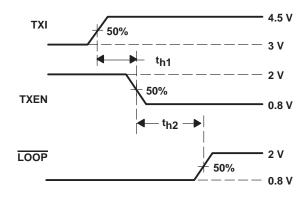
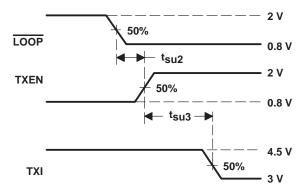
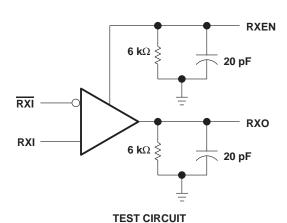


Figure 8



NOTE: Input  $t_f \le 5$  ns;  $t_f \le 5$  ns

Figure 9



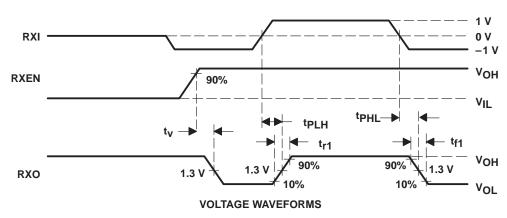


Figure 10. Test Circuit and Voltage Waveforms



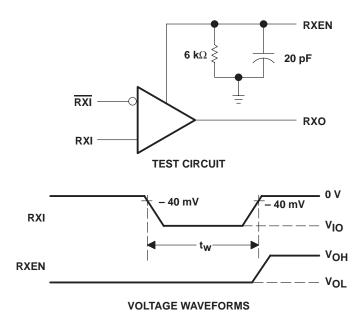


Figure 11. Test Circuit and Voltage Waveforms

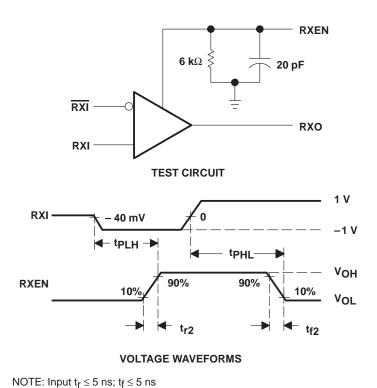
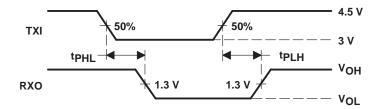


Figure 12. Test Circuit and Voltage Waveforms



NOTE: Input  $t_r \le 5$  ns;  $t_f \le 5$  ns

Figure 13

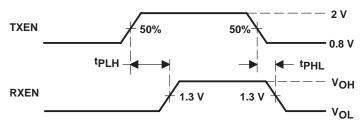


Figure 14

#### **IMPORTANT NOTICE**

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

Copyright © 1998, Texas Instruments Incorporated